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Description

The 9DBV0841 is a 1.8V member of IDT's full featured PCIe family. It has integrated output terminations providing $Z_o=100\Omega$ for direct connection for 100Ω transmission lines. The device has 8 output enables for clock management and 3 selectable SMBus addresses.

Recommended Application

SSD, microServers, WLAN Access points

Output Features

- 8 – 1-200Hz Low-Power (LP) HCSL DIF pairs

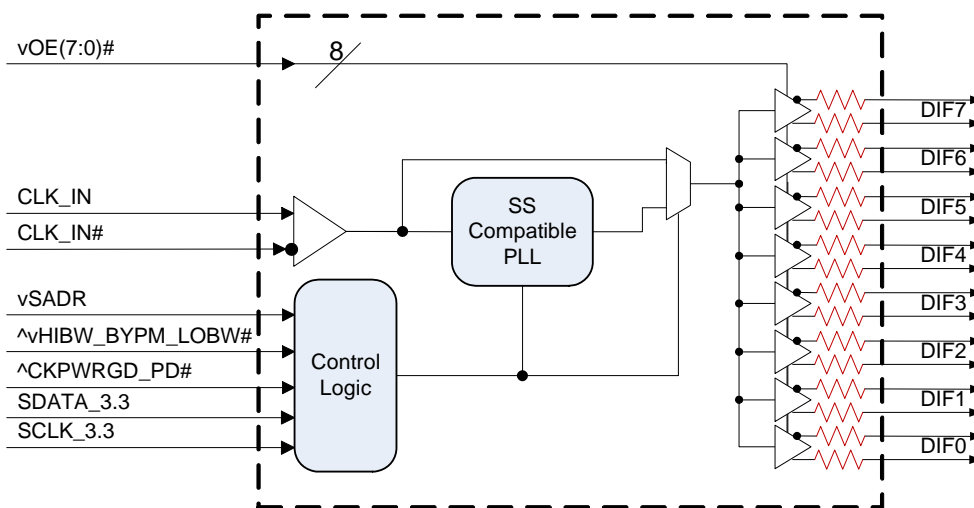
Key Specifications

- DIF cycle-to-cycle jitter <50ps
- DIF output-to-output skew <50ps
- DIF *additive* phase jitter is <100fs rms for PCIe Gen3
- DIF *additive* phase jitter <300fs rms for 12k-20MHz

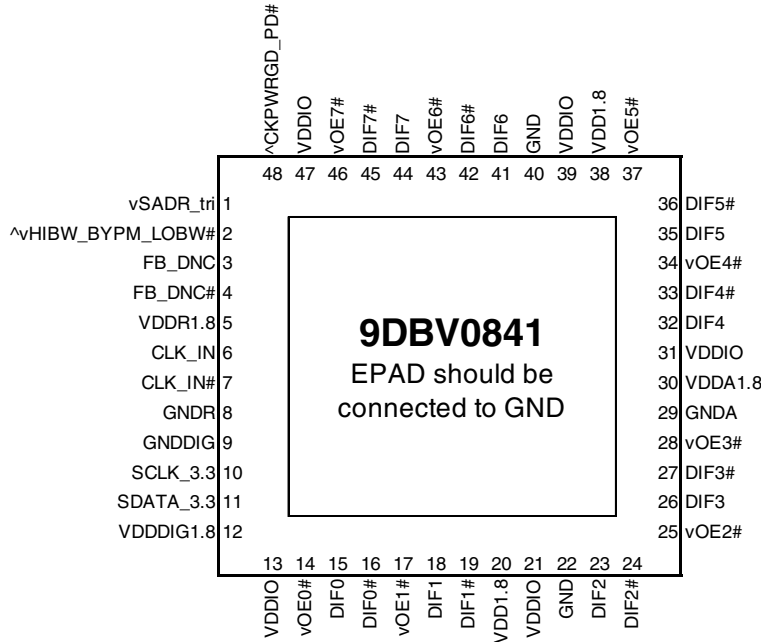
Features/Benefits

- LP-HCSL outputs save 32 resistors; minimal board space and BOM cost
- 62mW typical power consumption in PLL mode; eliminates thermal concerns
- Spread Spectrum (SS) compatible; allows use of SS for EMI reduction
- OE# pins; support DIF power management
- HCSL compatible differential input; can be driven by common clock sources
- Programmable Slew rate for each output; allows tuning for various line lengths
- Programmable output amplitude; allows tuning for various application environments
- Pin/software selectable PLL bandwidth and PLL Bypass; minimize phase jitter for each application
- Outputs blocked until PLL is locked; clean system start-up
- Software selectable 50MHz or 125MHz PLL operation; useful for Ethernet applications
- Configuration can be accomplished with strapping pins; SMBus interface not required for device control
- 3.3V tolerant SMBus interface works with legacy controllers
- Space saving 48-pin 6x6mm VFQFPN; minimal board space
- Selectable SMBus addresses; multiple devices can easily share an SMBus segment

Block Diagram



Pin Configuration



48-pin VFQFPN, 6x6 mm, 0.4mm pitch

- ^v prefix indicates internal 120KOhm pull up *AND* pull down resistor (biased to VDD/2)
- v prefix indicates internal 120KOhm pull down resistor
- ^ prefix indicates internal 120KOhm pull up resistor

SMBus Address Selection Table

	SADR	Address	+ Read/Write bit
State of SADR on first application of CKPWRGD_PD#	0	1101011	x
	M	1101100	x
	1	1101101	x

Power Management Table

CKPWRGD_PD#	CLK_IN	SMBus OEx bit	OEx# Pin	DIFx		PLL
				True O/P	Comp. O/P	
0	X	X	X	Low	Low	Off
1	Running	0	X	Low	Low	On ¹
1	Running	1	0	Running	Running	On ¹
1	Running	1	1	Low	Low	On ¹

1. If Bypass mode is selected, the PLL will be off, and outputs will be running.

Power Connections

Pin Number		Description
VDD	VDDIO	
5		Input receiver analog
12		Digital Power
20, 31, 38	13, 21, 31, 39, 47	DIF outputs
30		PLL Analog

Frequency Select Table

FSEL Byte3 [4:3]	CLK_IN (MHz)	DIFx (MHz)
00 (Default)	100.00	CLK_IN
01	50.00	CLK_IN
10	125.00	CLK_IN
11	Reserved	Reserved

PLL Operating Mode

HiBW BypM LoBW#	MODE	Byte1 [7:6] Readback	Byte1 [4:3] Control
0	PLL Lo BW	00	00
M	Bypass	01	01
1	PLL Hi BW	11	11

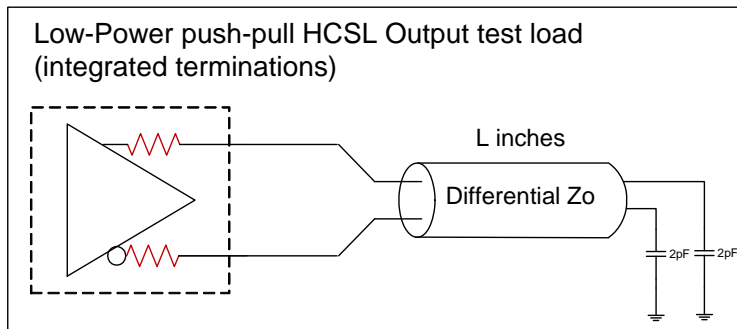
Pin Descriptions

PIN #	PIN NAME	TYPE	DESCRIPTION
1	vSADR_tri	LATCHED IN	Tri-level latch to select SMBus Address. See SMBus Address Selection Table.
2	^vHIBW_BYPM_LOBW#	LATCHED IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.
3	FB_DNC	DNC	True clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin.
4	FB_DNC#	DNC	Complement clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin.
5	VDDR1.8	PWR	1.8V power for differential input clock (receiver). This VDD should be treated as an Analog power rail and filtered appropriately.
6	CLK_IN	IN	True Input for differential reference clock.
7	CLK_IN#	IN	Complementary Input for differential reference clock.
8	GNDR	GND	Analog Ground pin for the differential input (receiver)
9	GNDDIG	GND	Ground pin for digital circuitry
10	SCLK_3.3	IN	Clock pin of SMBus circuitry, 3.3V tolerant.
11	SDATA_3.3	I/O	Data pin for SMBus circuitry, 3.3V tolerant.
12	VDDDIG1.8	PWR	1.8V digital power (dirty power)
13	VDDIO	PWR	Power supply for differential outputs
14	vOE0#	IN	Active low input for enabling DIF pair 0. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
15	DIF0	OUT	Differential true clock output
16	DIF0#	OUT	Differential Complementary clock output
17	vOE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
18	DIF1	OUT	Differential true clock output
19	DIF1#	OUT	Differential Complementary clock output
20	VDD1.8	PWR	Power supply, nominal 1.8V
21	VDDIO	PWR	Power supply for differential outputs
22	GND	GND	Ground pin.
23	DIF2	OUT	Differential true clock output
24	DIF2#	OUT	Differential Complementary clock output
25	vOE2#	IN	Active low input for enabling DIF pair 2. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
26	DIF3	OUT	Differential true clock output
27	DIF3#	OUT	Differential Complementary clock output
28	vOE3#	IN	Active low input for enabling DIF pair 3. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
29	GNDA	GND	Ground pin for the PLL core.
30	VDDA1.8	PWR	1.8V power for the PLL core.
31	VDDIO	PWR	Power supply for differential outputs
32	DIF4	OUT	Differential true clock output
33	DIF4#	OUT	Differential Complementary clock output
34	vOE4#	IN	Active low input for enabling DIF pair 4. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
35	DIF5	OUT	Differential true clock output
36	DIF5#	OUT	Differential Complementary clock output
37	vOE5#	IN	Active low input for enabling DIF pair 5. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
38	VDD1.8	PWR	Power supply, nominal 1.8V

Pin Descriptions (cont.)

PIN #	PIN NAME	TYPE	DESCRIPTION
39	VDDIO	PWR	Power supply for differential outputs
40	GND	GND	Ground pin.
41	DIF6	OUT	Differential true clock output
42	DIF6#	OUT	Differential Complementary clock output
43	vOE6#	IN	Active low input for enabling DIF pair 6. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
44	DIF7	OUT	Differential true clock output
45	DIF7#	OUT	Differential Complementary clock output
46	vOE7#	IN	Active low input for enabling DIF pair 7. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
47	VDDIO	PWR	Power supply for differential outputs
48	^CKPWRGD_PD#	IN	Input notifies device to sample latched inputs and start up on first high assertion. Low enters Power Down Mode, subsequent high assertions exit Power Down Mode. This pin has internal pull-up resistor.
49	epad	GND	Connect epad to ground

Test Loads



L = 5 inches

Alternate Terminations

The 9DBV family can easily drive LVPECL, LVDS, and CML logic. See [“AN-891 Driving LVPECL, LVDS, and CML Logic with IDT's "Universal" Low-Power HCSL Outputs”](#) for details.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9DBV0841. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
1.8V Supply Voltage	VDDxx	Applies to VDD, VDDA and VDDIO	-0.5		2.5	V	1,2
Input Voltage	V _{IN}		-0.5		V _{DD} +0.5V	V	1, 3
Input High Voltage, SMBus	V _{IHSMB}	SMBus clock and data pins			3.6V	V	1
Storage Temperature	T _s		-65		150	°C	1
Junction Temperature	T _j				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

²Operation under these conditions is neither implied nor guaranteed.

³Not to exceed 2.5V.

Electrical Characteristics—Clock Input Parameters

T_A = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Common Mode Voltage - DIF_IN	V _{COM}	Common Mode Input Voltage	150		1000	mV	1
Input Swing - DIF_IN	V _{SWING}	Differential value	300			mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I _{IN}	V _{IN} = V _{DD} , V _{IN} = GND	-5		5	uA	
Input Duty Cycle	d _{tin}	Measurement from differential waveform	45		55	%	1
Input Jitter - Cycle to Cycle	J _{DIFIn}	Differential Measurement	0		125	ps	1

¹Guaranteed by design and characterization, not 100% tested in production.

²Slew rate measured through +/-75mV window centered around differential zero

Electrical Characteristics–Input/Supply/Common Parameters–Normal Operating Conditions

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx	Supply voltage for core and analog	1.7	1.8	1.9	V	
Output Supply Voltage	VDDIO	Supply voltage for Low Power HCSL Outputs	0.9975	1.05	1.9	V	
Ambient Operating Temperature	T _{AMB}	Commercial range	0	25	70	°C	
		Industrial range	-40	25	85	°C	
Input High Voltage	V _{IH}	Single-ended inputs, except SMBus	0.75 V _{DD}		V _{DD} + 0.3	V	
Input Mid Voltage	V _{IM}	Single-ended tri-level inputs ('_tri' suffix)	0.4 V _{DD}		0.6 V _{DD}	V	
Input Low Voltage	V _{IL}	Single-ended inputs, except SMBus	-0.3		0.25 V _{DD}	V	
Input Current	I _{IN}	Single-ended inputs, V _{IN} = GND, V _{IN} = VDD	-5		5	uA	
	I _{INP}	Single-ended inputs V _{IN} = 0 V; Inputs with internal pull-up resistors V _{IN} = VDD; Inputs with internal pull-down resistors	-200		200	uA	
Input Frequency	F _{ibyp}	Bypass mode	1		200	MHz	2
	F _{ipll}	100MHz PLL mode	60	100.00	140	MHz	2
	F _{ipll}	125MHz PLL mode	75	125.00	175	MHz	2
	F _{ipll}	50MHz PLL mode	30	50.00	65	MHz	2
Pin Inductance	L _{pin}			7	nH	1	
Capacitance	C _{IN}	Logic Inputs, except DIF_IN	1.5		5	pF	1
	C _{INDIF_IN}	DIF_IN differential clock inputs	1.5		2.7	pF	1,5
	C _{OUT}	Output pin capacitance			6	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.6	1	ms	1,2
Input SS Modulation Frequency PCIe	f _{MODINPCIe}	Allowable Frequency for PCIe Applications (Triangular Modulation)	30		33	kHz	
Input SS Modulation Frequency non-PCIe	f _{MODIN}	Allowable Frequency for non-PCIe Applications (Triangular Modulation)	0		66	kHz	
OE# Latency	t _{LATOE#}	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	clocks	1,3
Tdrive_PD#	t _{DRVPD}	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t _F	Fall time of single-ended control inputs			5	ns	2
Trise	t _R	Rise time of single-ended control inputs				ns	2
SMBus Input Low Voltage	V _{ILSMB}	V _{DDSMB} = 3.3V, see note 4 for V _{DDSMB} < 3.3V			0.6	V	
SMBus Input High Voltage	V _{IHSMB}	V _{DDSMB} = 3.3V, see note 5 for V _{DDSMB} < 3.3V	2.1		3.6	V	4
SMBus Output Low Voltage	V _{OLSMB}	@ I _{PULLUP}			0.4	V	
SMBus Sink Current	I _{PULLUP}	@ V _{OL}	4			mA	
Nominal Bus Voltage	V _{DDSMB}	Bus Voltage	1.7		3.6	V	
SCLK/SDATA Rise Time	t _{RSMB}	(Max V _{IL} - 0.15) to (Min V _{IH} + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t _{FSMB}	(Min V _{IH} + 0.15) to (Max V _{IL} - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			400	kHz	6

¹Guaranteed by design and characterization, not 100% tested in production.

²Control input must be monotonic from 20% to 80% of input swing.

³Time from deassertion until outputs are >200 mV

⁴For V_{DDSMB} < 3.3V, V_{IHSMB} ≥ 0.8xV_{DDSMB}

⁵DIF_IN input

⁶The differential input clock must be running for the SMBus to be active

Electrical Characteristics–Low Power HCSL Outputs

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	dV/dt	Scope averaging on, fast setting	1.7	2.8	4	V/ns	1,2,3
	dV/dt	Scope averaging on, slow setting	1.1	2.1	3.2	V/ns	1,2,3
Slew rate matching	Δ dV/dt	Slew rate matching, Scope averaging on		6.2	20	%	1,2,4
Voltage High	V _{HIGH}	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on)	660	789	850	mV	7
Voltage Low	V _{LOW}		-150	38	150		7
Max Voltage	V _{max}	Measurement on single ended signal using absolute value. (Scope averaging off)		803	1150	mV	7
Min Voltage	V _{min}		-300	15			7
Crossing Voltage (abs)	V _{cross_abs}	Scope averaging off	250	417	550	mV	1,5
Crossing Voltage (var)	Δ -V _{cross}	Scope averaging off		13	140	mV	1,6

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Slew rate is measured through the V_{swing} voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ V_{cross} is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all V_{cross} measurements in any particular system. Note that this is a subset of V_{cross_min/max} (V_{cross} absolute) allowed. The intent is to limit V_{cross} induced modulation by setting Δ -V_{cross} to be smaller than V_{cross} absolute.

⁷ At default SMBus settings.

Electrical Characteristics–Current Consumption

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I _{DDA}	VDDA+VDDR, PLL Mode, @100MHz		10.6	15	mA	1
	I _{DD}	VDD, All outputs active @100MHz		6.1	10	mA	1
	I _{DDO}	VDDO, All outputs active @100MHz		30.7	35	mA	1
Powerdown Current	I _{DDAPD}	VDDA+VDDR, PLL Mode, @100MHz		0.58	1	mA	1, 2
	I _{DDPD}	VDD, Outputs Low/Low		0.81	2	mA	1, 2
	I _{DDOPD}	VDDO, Outputs Low/Low		0.00	0.01	mA	1, 2

¹ Guaranteed by design and characterization, not 100% tested in production.

² Input clock stopped.

Electrical Characteristics–Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PLL Bandwidth	BW	-3dB point in High BW Mode	2	2.7	4	MHz	1,5
		-3dB point in Low BW Mode	1	1.4	2	MHz	1,5
PLL Jitter Peaking	t _{JPEAK}	Peak Pass band Gain		1.1	2	dB	1
Duty Cycle	t _{DC}	Measured differentially, PLL Mode	45	50.1	55	%	1
Duty Cycle Distortion	t _{DCD}	Measured differentially, Bypass Mode @100MHz	-1	0.03	1	%	1,3
Skew, Input to Output	t _{pdBYP}	Bypass Mode, V _T = 50%	2800	3625	4500	ps	1
	t _{pdPLL}	PLL Mode V _T = 50%	-100	-4	100	ps	1,4
Skew, Output to Output	t _{sk3}	V _T = 50%		39	50	ps	1,4
Jitter, Cycle to cycle	t _{jyc-cyc}	PLL mode		14	50	ps	1,2
		Additive Jitter in Bypass Mode		0.10	25	ps	1,2

¹ Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

⁴ All outputs at default slew rate

⁵ The MIN/TYP/MAX values of each BW setting track each other, i.e., Low BW MAX will never occur with Hi BW MIN.

Electrical Characteristics–Phase Jitter Parameters

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	INDUSTRY LIMIT	UNITS	Notes
Phase Jitter, PLL Mode	t _{jphPCleG1}	PCIe Gen 1		24	32	86	ps (p-p)	1,2,3,5
	t _{jphPCleG2}	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.5	0.8	3	ps (rms)	1,2,3,5
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		1.7	2.3	3.1	ps (rms)	1,2,3,5
	t _{jphPCleG3}	PCIe Gen 3 (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.4	0.6	1	ps (rms)	1,2,3,5
t _{jphSGMII}	125MHz, 1.5MHz to 10MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz			2.0		NA	ps (rms)	1,6
Additive Phase Jitter, Bypass Mode	t _{jphPCleG1}	PCIe Gen 1		0.6	2.6	N/A	ps (p-p)	1,2,3,5
	t _{jphPCleG2}	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.1	0.3	N/A	ps (rms)	1,2,3,4,5
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.14	0.2	N/A	ps (rms)	1,2,3,4
	t _{jphPCleG3}	PCIe Gen 3 (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.00	0.1	N/A	ps (rms)	1,2,3,4
t _{jphSGMII}	125MHz, 1.5MHz to 10MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz			0.27		N/A	ps (rms)	1,6

¹ Guaranteed by design and characterization, not 100% tested in production.

² See <http://www.pcisig.com> for complete specs

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ For RMS figures, additive jitter is calculated by solving the following equation: Additive jitter = SQRT[(total jitter)² - (input jitter)²]

⁵ Driven by 9FGV0841/9FGL0841 or equivalent

⁶ Driven by Rohde&Schartz SMA100

General SMBus Serial Interface Information

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte **N through Byte N+X-1**
- IDT clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

Index Block Write Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRite		
Beginning Byte = N			ACK
			ACK
Data Byte Count = X			ACK
Beginning Byte N		X Byte	ACK
O			O
O			O
O			O
Byte N + X - 1			ACK
P	stoP bit		

Note: SMBus Address is Latched on SADR pin.

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte **N+X-1**
- IDT clock sends **Byte 0 through Byte X (if X_(H) was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Read Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRite		
Beginning Byte = N			ACK
			ACK
RT	Repeat starT		
Slave Address			
RD	ReaD		ACK
ACK			Data Byte Count=X
			Beginning Byte N
ACK		X Byte	O
O			O
O			O
O			
			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

SMBus Table: Output Enable Register ¹

Byte 0	Name	Control Function	Type	0	1	Default
Bit 7	DIF OE7	Output Enable	RW	Low/Low	OE7# control	1
Bit 6	DIF OE6	Output Enable	RW	Low/Low	OE6# control	1
Bit 5	DIF OE5	Output Enable	RW	Low/Low	OE5# control	1
Bit 4	DIF OE4	Output Enable	RW	Low/Low	OE4# control	1
Bit 3	DIF OE3	Output Enable	RW	Low/Low	OE3# control	1
Bit 2	DIF OE2	Output Enable	RW	Low/Low	OE2# control	1
Bit 1	DIF OE1	Output Enable	RW	Low/Low	OE1# control	1
Bit 0	DIF OE0	Output Enable	RW	Low/Low	OE0# control	1

1. A low on these bits will override the OE# pin and force the differential output Low/Low

SMBus Table: PLL Operating Mode and Output Amplitude Control Register

Byte 1	Name	Control Function	Type	0	1	Default
Bit 7	PLLMODERB1	PLL Mode Readback Bit 1	R	See PLL Operating Mode Table		Latch
Bit 6	PLLMODERB0	PLL Mode Readback Bit 0	R			Latch
Bit 5	PLLMODE_SWCNTRL	Enable SW control of PLL Mode	RW	Values in B1[7:6] set PLL Mode	Values in B1[4:3] set PLL Mode	0
Bit 4	PLLMODE1	PLL Mode Control Bit 1	RW ¹	See PLL Operating Mode Table		0
Bit 3	PLLMODE0	PLL Mode Control Bit 0	RW ¹			0
Bit 2	Reserved					1
Bit 1	AMPLITUDE 1	Controls Output Amplitude	RW	00 = 0.6V	01 = 0.7V	1
Bit 0	AMPLITUDE 0		RW	10 = 0.8V	11 = 0.9V	0

1. B1[5] must be set to a 1 for these bits to have any effect on the part.

SMBus Table: DIF Slew Rate Control Register

Byte 2	Name	Control Function	Type	0	1	Default
Bit 7	SLEWRATESEL DIF7	Adjust Slew Rate of DIF7	RW	Slow setting	Fast setting	1
Bit 6	SLEWRATESEL DIF6	Adjust Slew Rate of DIF6	RW	Slow setting	Fast setting	1
Bit 5	SLEWRATESEL DIF5	Adjust Slew Rate of DIF5	RW	Slow setting	Fast setting	1
Bit 4	SLEWRATESEL DIF4	Adjust Slew Rate of DIF4	RW	Slow setting	Fast setting	1
Bit 3	SLEWRATESEL DIF3	Adjust Slew Rate of DIF3	RW	Slow setting	Fast setting	1
Bit 2	SLEWRATESEL DIF2	Adjust Slew Rate of DIF2	RW	Slow setting	Fast setting	1
Bit 1	SLEWRATESEL DIF1	Adjust Slew Rate of DIF1	RW	Slow setting	Fast setting	1
Bit 0	SLEWRATESEL DIF0	Adjust Slew Rate of DIF0	RW	Slow setting	Fast setting	1

SMBus Table: Frequency Select Control Register

Byte 3	Name	Control Function	Type	0	1	Default
Bit 7	Reserved					1
Bit 6	Reserved					1
Bit 5	FREQ_SEL_EN	Enable SW selection of frequency	RW	SW frequency change disabled	SW frequency change enabled	0
Bit 4	FSEL1	Freq. Select Bit 1	RW ¹	See Frequency Select Table		0
Bit 3	FSEL0	Freq. Select Bit 0	RW ¹			0
Bit 2	Reserved					1
Bit 1	Reserved					1
Bit 0	SLEWRATESEL FB	Adjust Slew Rate of FB	RW	Slow setting	Fast setting	1

1. B3[5] must be set to a 1 for these bits to have any effect on the part.

Byte 4 is Reserved and reads back 'hFF'

SMBus Table: Revision and Vendor ID Register

Byte 5	Name	Control Function	Type	0	1	Default
Bit 7	RID3	Revision ID	R	A rev = 0000		0
Bit 6	RID2		R			0
Bit 5	RID1		R			0
Bit 4	RID0		R			0
Bit 3	VID3	VENDOR ID	R	0001 = IDT		0
Bit 2	VID2		R			0
Bit 1	VID1		R			0
Bit 0	VID0		R			1

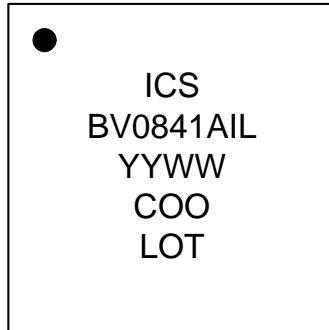
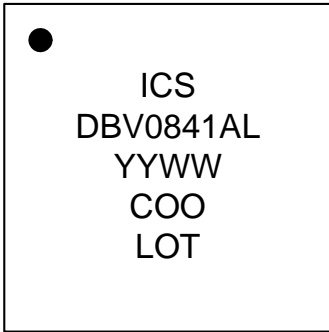
SMBus Table: Device Type/Device ID

Byte 6	Name	Control Function	Type	0	1	Default
Bit 7	Device Type1	Device Type	R	00 = FGx, 01 = DBx, 10 = DMx, 11= Reserved		0
Bit 6	Device Type0		R			1
Bit 5	Device ID5	Device ID	R	001000 binary or 08 hex		0
Bit 4	Device ID4		R			0
Bit 3	Device ID3		R			1
Bit 2	Device ID2		R			0
Bit 1	Device ID1		R			0
Bit 0	Device ID0		R			0

SMBus Table: Byte Count Register

Byte 7	Name	Control Function	Type	0	1	Default
Bit 7	Reserved					0
Bit 6	Reserved					0
Bit 5	Reserved					0
Bit 4	BC4	Byte Count Programming	RW	Writing to this register will configure how many bytes will be read back, default is = 8 bytes.		0
Bit 3	BC3		RW			1
Bit 2	BC2		RW			0
Bit 1	BC1		RW			0
Bit 0	BC0		RW			0

Marking Diagrams



Notes:

1. "LOT" is the lot sequence number.
2. "COO" denotes country of origin.
3. YYWW is the last two digits of the year and week that the part was assembled.
4. Line 2: truncated part number
5. "L" denotes RoHS compliant package.
6. "I" denotes industrial temperature range device.

Thermal Characteristics

PARAMETER	SYMBOL	CONDITIONS	PKG	TYP VALUE	UNITS	NOTES
Thermal Resistance	θ_{JC}	Junction to Case	NDG48	33	°C/W	1
	θ_{Jb}	Junction to Base		2.1	°C/W	1
	$\theta_{JA0\theta}$	Junction to Air, still air		37	°C/W	1
	θ_{JA1}	Junction to Air, 1 m/s air flow		30	°C/W	1
	θ_{JA3}	Junction to Air, 3 m/s air flow		27	°C/W	1
	θ_{JA5}	Junction to Air, 5 m/s air flow		26	°C/W	1

¹ePad soldered to board

Package Outline and Dimensions (NDG48)

REVISONS		DATE	APPROVED
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	02/26/16	JH

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- ALL DIMENSIONS ARE IN MILLIMETERS.
- N REFERS TO THE NUMBER OF LEADS.
- ND AND NE REFER TO THE NUMBER OF LEADS PER SIDE.

SYMBOL	DIMENSION		
	MIN	NOM	MAX
D2	3.95	4.10	4.20
E2	3.95	4.10	4.20
L	0.30	0.40	0.50
K	0.55 REF		
D	6.00 BSC		
E	6.00 BSC		
e	0.40 BSC		
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	---	0.20 REF	---
N	48		
ND	12		
NE	12		
b	0.15	0.20	0.25

TOLERANCE OF FORM & POSITION	
aaa	0.10
bbb	0.07
ccc	0.10
ddd	0.05
eee	0.08
fff	0.10

TOP VIEW

SIDE VIEW

BOTTOM VIEW

FRONT VIEW

TOLERANCES UNLESS SPECIFIED

DECIMAL	ANGULAR
±1	±1
X.X	
X.XX	
XXX.X	

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APPROVALS	DATE	TITLE
RAC	02/26/16	ND/NDG 48 PACKAGE OUTLINE
CHECKED		6.0 x 6.0 mm BODY 4.1x4.1mm EPAD 0.40 mm PITCH QFN
		SIZE DRAWING No.
		C PSC-4212-01
		REV 00
		DO NOT SCALE DRAWING
		SHEET 1 OF 2

Package Outline and Dimensions (NDG48), cont.

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	02/26/16	JH

RECOMMENDED LAND PATTERN DIMENSION

NOTES:

1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
2. TOP DOWN VIEW, AS VIEWED ON PCB.
3. COMPONENT OUTLINE SHOWS FOR REFERENCE IN GREEN.
4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPECIFIED DECIMAL ±.1 XX± XXX±	APPROVALS DRAWN RAC CHECKED	DATE 02/26/16	REV 00
		6024 Silver Creek Valley Road San Jose CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591 WWW.IDT.COM	
TITLE: ND/NDG 48 PACKAGE OUTLINE 6.0 x 6.0 mm BODY 4.1x4.1mm EPAD 0.40 mm PITCH QFN		SIZE: C DRAWING No. PSC-4212-01	
DO NOT SCALE DRAWING			SHEET 2 OF 2

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9DBV0841AKLF	Trays	48-pin VFQFPN	0 to +70° C
9DBV0841AKLFT	Tape and Reel	48-pin VFQFPN	0 to +70° C
9DBV0841AKILF	Trays	48-pin VFQFPN	-40 to +85° C
9DBV0841AKILFT	Tape and Reel	48-pin VFQFPN	-40 to +85° C

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

"A" is the device revision designator (will not correlate with the datasheet revision).

Revision History

Rev.	Initiator	Issue Date	Description	Page #
A	RDW	8/13/2012	<ol style="list-style-type: none"> 1. Removed "Differential" from DS title and Recommended Application, corrected typo's in Description. Updated block diagram to show integrated terminations. 2. Removed references to 60KOhm pulldown under pinout. 3. Updated "Phase Jitter Parameters" table by adding "Industry Limit" column and updated all Electrical Tables with characterization data. 4. Updated Byte3[0] to be consistent with Byte 2. Updated Byte6[7:6] definition. 5. Updated Mark spec with correct part revision (A) and added thermal data to page 13. 6. Added NDG48 to "Package Outline and Package Dimensions" on page 14 and updated Ordering information to correct part revision (A rev). 7. Move to final 	1,2,6-9,11,13,14
B	RDW	2/18/2013	<ol style="list-style-type: none"> 1. Changed VIH min. from 0.65*VDD to 0.75*VDD 2. Changed VIL max. from 0.35*VDD to 0.25*VDD 3. Added missing mid-level input voltage spec (VIM) of 0.4*VDD to 0.6*VDD. 	7
C	RDW	8/12/2014	Changed package designator from "MLF" to "VFQFPN"	Various
D	RDW	3/10/2016	<ol style="list-style-type: none"> 1. Numerous typographical and grammatical updates for document consistency with other devices in the family, including updated descriptions for Bytes 0 and 2. 2. Fast and slow slew rates were swapped in the "DIF 0.7V Low Power HCSL Outputs" table. 3. Changed PCIe clock source from 9FG432 to 9FGV0841/9FGL0841 for PLL mode phase jitter numbers. New phase jitter numbers are lower. 4. Added epad to pinout diagram and pin descriptions. 5. Updated Clock Input Parameters to be consistent with PCIe Vswing parameter. 6. Updated package drawing to latest format. 	Various
E	RDW	4/28/2016	<ol style="list-style-type: none"> 1. Updated max frequency of 100MHz PLL mode to 140MHz 2. Updated max frequency of 125MHz PLL mode to 175MHz 3. Updated max frequency of 50MHz PLL mode to 65MHz 	6



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